

ABSTRACT OF THE DISCLOSURE

A method of bonding a thermal interface layer to a heat dissipating member and the resulting device are described. The method may involve plating a bonding surface of the heat dissipating member, and bonding a metallic solder onto the plating under vacuum or inert conditions and substantially without the use of a solder flux. Also described, is a heat dissipating device having a thermal interface material layer bonded thereto for thermal coupling to a heat conducting component by an impermanent attachment.